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AT JMW

PATENT
450100-03654

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Katsuhiro DOI et al.
Serial No. : 09/996,518
For : MOLDING DIE APPARATUS AND MOLDING METHOD
Filed : November 29, 2001
Examiner : Luk, Emmanuel S.
Art Unit : 1722

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Sir:

Responsive to the Final Official Action mailed April 20, 2005, please amend the
above-identified application as follows:

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8/22/05
KRW
8/30/05